

Fig. 1

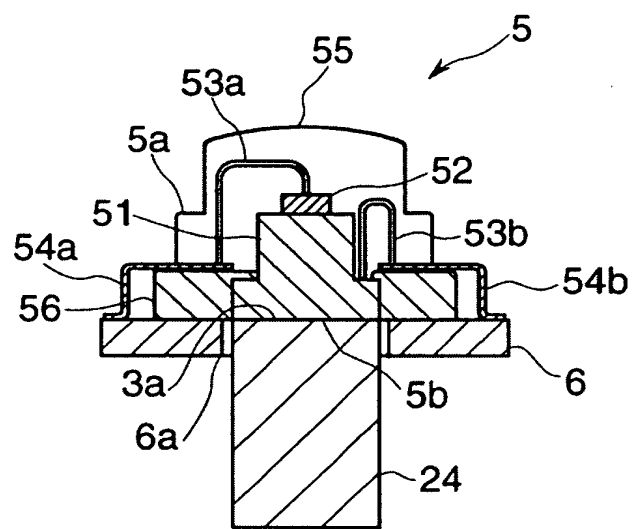


Fig.2

Temperature/Illumination Intensity Change of Light Irradiating Unit

	conventional arrangement (with heat dissipating sheet)	this invention no heat dissipating sheet (loosely joined)	this invention no heat dissipating sheet (tightly joined)
initial temperature of soldered face (°C)	24.2	25.5	27.2
soldered face temperature 60 min later	55.7	57.1	49.3
temperature rise (°C)	31.5	31.6	22.1
initial temperature of housing (°C)	24.3	25.4	26.8
housing temperature 60 min later (°C)	47	54.1	44.6
temperature rise (°C)	22.7	28.7	17.8
initial illumination intensity (lx)	134200	138000	138200
illumination intensity 60 min later (lx)	79200	97600	112000
deterioration rate	59%	71%	81%

Fig.3



Fig.4

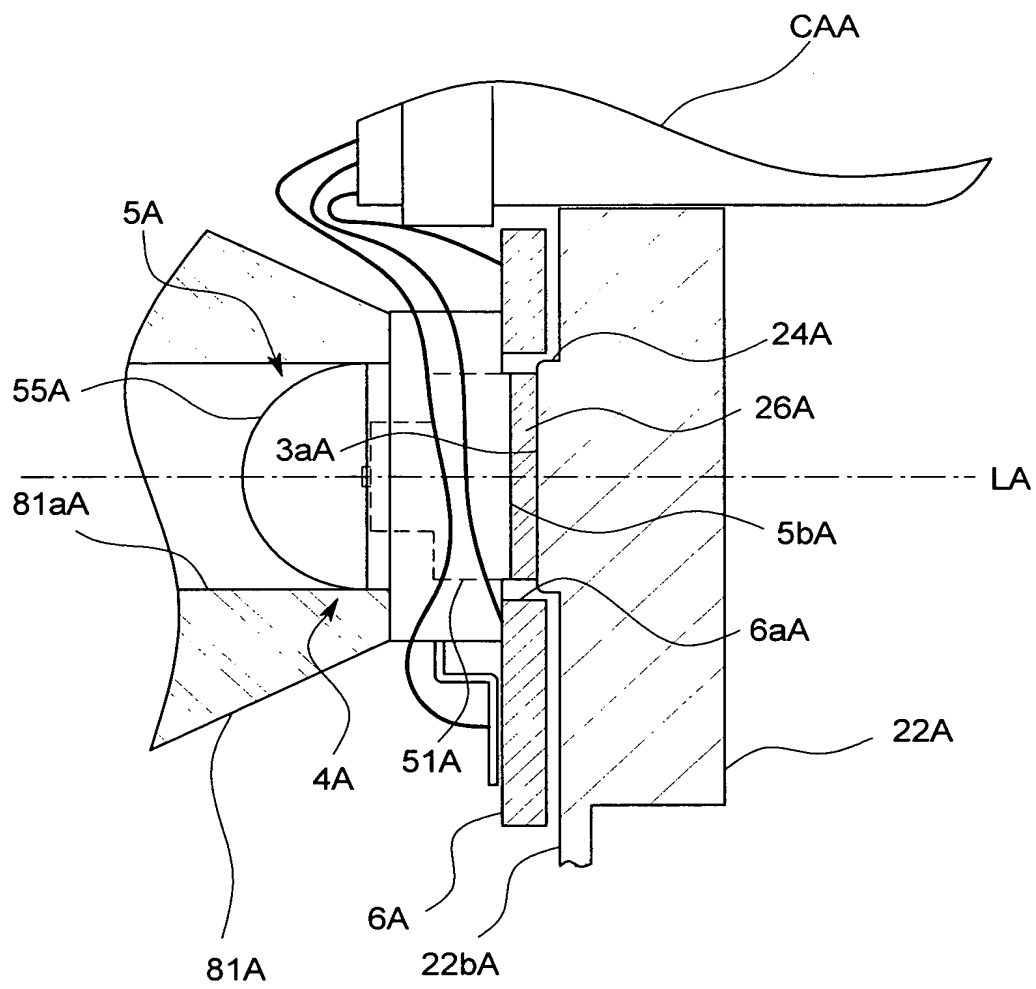


Fig.5

Temperature/Illumination Intesity Change of Light Irradiatin Unit

	conventional arrangement (red)	this invention (red) (tihgtly joined)
initial temperature of soldered face (°C)	25	27
soldered face temperature 60 min later	44	41
temperature rise (°C)	19	14
initial temperature of housing (°C)	25	27
housing temperature 60 min later (°C)	40	39
temperature rise (°C)	15	12
initial illumination intensity (lx)	155400	186900
illumination intensity 60 min later (lx)	129100	170300
deterioration rate	83%	91%

Fig.6

Temperature Change of Light Irradiating Unit

	this invention (blue) (loosely joined)	this invention (blue) (tightly joined)
initial temperature of soldered face (°C)	23	20.9
soldered face temperature	46	41.4
temperature rise (°C)	23	20.5
initial temperature of housing (°C)	23	20.9
housing temperature 60 min later (°C)	40	36.6
temperature rise (°C)	17	15.7

Fig. 7